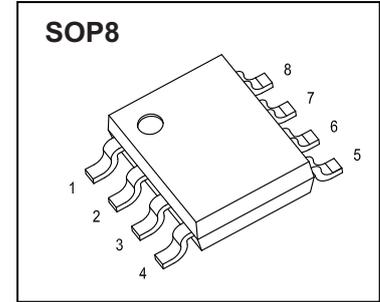


## SOP8 Plastic-Encapsulate MOSFETS

### CJQ4\* % N Channel +P Channel MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
40V	19mΩ@10V	8A
	29mΩ@4.5V	
-40V	35mΩ@-10V	-7A
	45mΩ@-4.5V	



#### FEATURE

- Surface Mount Package
- Super High Density Cell Design for Extremely Low  $R_{DS(ON)}$

#### APPLICATION

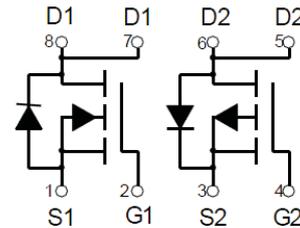
- CCFL Inverter

#### MARKING



Q4614= Device code  
 YY= Code  
 Solid dot = Pin1 indicator  
 Solid dot = Green molding compound device,  
 if none,the normal device.

#### Equivalent Circuit



#### ABSOLUTE MAXIMUM RATINGS ( $T_a=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
<b>N-MOSFET</b>			
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current (note 1)	$I_D$	8	A
Pulsed Drain Current ( $t_p=10\mu s$ )	$I_{DM}$	32	A
Continuous Source-Drain Diode Current	$I_S$	8	A
<b>P-MOSFET</b>			
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current (note 1)	$I_D$	-7	A
Pulsed Drain Current ( $t_p=10\mu s$ )	$I_{DM}$	-28	A
Continuous Source-Drain Diode Current	$I_S$	-7	A
<b>Temperature and Thermal Resistance</b>			
Power Dissipation	$P_D$	2	W
Thermal Resistance from Junction to Ambient (note 1)	$R_{\theta JA}$	62.5	$^{\circ}C/W$
Junction Temperature	$T_J$	150	$^{\circ}C$
Storage Temperature	$T_{STG}$	-55~+150	$^{\circ}C$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	$T_L$	260	$^{\circ}C$

# MOSFET ELECTRICAL CHARACTERISTICS

## N-ch MOSFET ELECTRICAL CHARACTERISTICS( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC CHARACTERISTICS</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 40V, V_{GS} = 0V$			1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Gate threshold voltage (note 2)	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2	V
Drain-source on-resistance(note 2)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 8A$		16	19	$m\Omega$
		$V_{GS} = 4.5V, I_D = 4A$		24	29	$m\Omega$
Forward tranconductance(note 2)	$g_{FS}$	$V_{DS} = 5V, I_D = 8A$		10		S
Diode forward voltage	$V_{SD}$	$I_S = 8A, V_{GS} = 0V$			1.2	V
<b>DYNAMIC CHARACTERISTICS (note 4)</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 20V, V_{GS} = 0V, f = 1MHz$		415		pF
Output Capacitance	$C_{oss}$			112		pF
Reverse Transfer Capacitance	$C_{rss}$			11		pF
<b>SWITCHING CHARACTERISTICS (note 3,4)</b>						
Turn-on delay time	$t_{d(on)}$	$V_{GEN} = 10V, V_{DD} = 20V,$ $R_G = 3\Omega, R_L = 2.5\Omega$		4		ns
Turn-on rise time	$t_r$			3		ns
Turn-off delay time	$t_{d(off)}$			15		ns
Turn-off fall time	$t_f$			2		ns
Total Gate Charge	$Q_g$	$V_{DS} = 20V, I_D = 8A,$ $V_{GS} = 10V$		12		nC
Gate-Source Charge	$Q_{gs}$			3.2		nC
Gate-Drain Charge	$Q_{gd}$			3.1		nC

## P-ch MOSFET ELECTRICAL CHARACTERISTICS( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC CHARACTERISTICS</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-40			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = -40V, V_{GS} = 0V$			-1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Gate threshold voltage (note 2)	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.5	-2	V
Drain-source on-resistance(note 2)	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -8A$		30	35	$m\Omega$
		$V_{GS} = -4.5V, I_D = -4A$		40	45	$m\Omega$
Forward tranconductance(note 2)	$g_{FS}$	$V_{DS} = -5V, I_D = -8A$		16		S
Diode forward voltage	$V_{SD}$	$I_S = -10A, V_{GS} = 0V$			-1.2	V
<b>DYNAMIC CHARACTERISTICS (note 4)</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -20V, V_{GS} = 0V, f = 1MHz$		520		pF
Output Capacitance	$C_{oss}$			100		pF
Reverse Transfer Capacitance	$C_{rss}$			65		pF
<b>SWITCHING CHARACTERISTICS (note 3,4)</b>						
Turn-on delay time	$t_{d(on)}$	$V_{GEN} = -10V, V_{DD} = -20V,$ $R_G = 6\Omega, R_L = 2.3\Omega$		7.5		ns
Turn-on rise time	$t_r$			5.5		ns
Turn-off delay time	$t_{d(off)}$			19		ns
Turn-off fall time	$t_f$			7		ns
Total Gate Charge	$Q_g$	$V_{DS} = -20V, I_D = -8A,$ $V_{GS} = -10V$		13		nC
Gate-Source Charge	$Q_{gs}$			3.8		nC
Gate-Drain Charge	$Q_{gd}$			3.1		nC

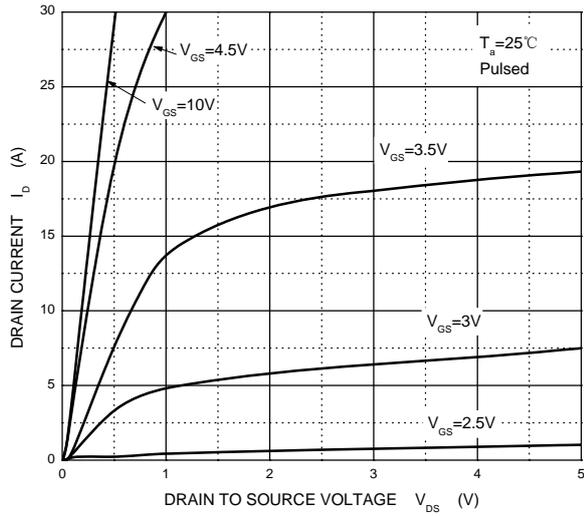
### Notes :

1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse width=300 $\mu s$ , duty cycle $\leq 2\%$ .
3. Switching characteristics are independent of operating junction temperature.
4. Granted by design, not subject to producing.

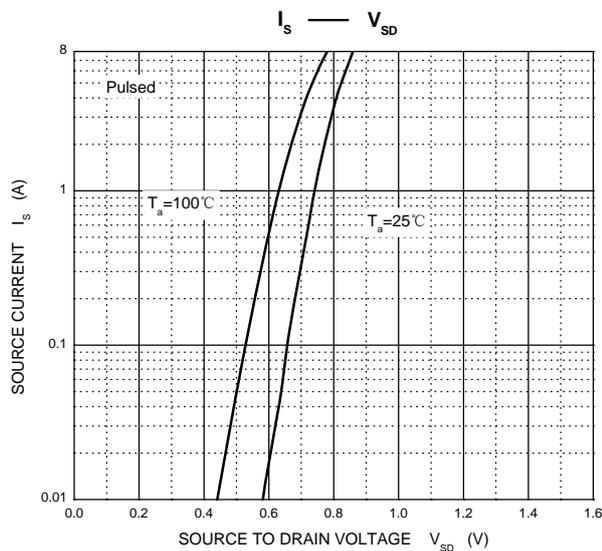
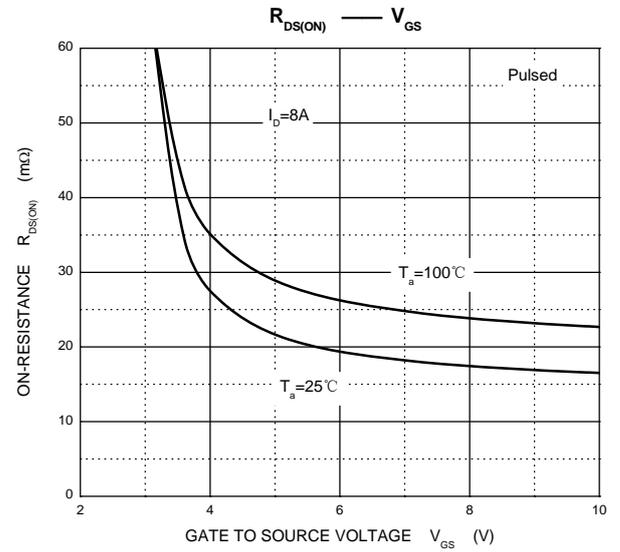
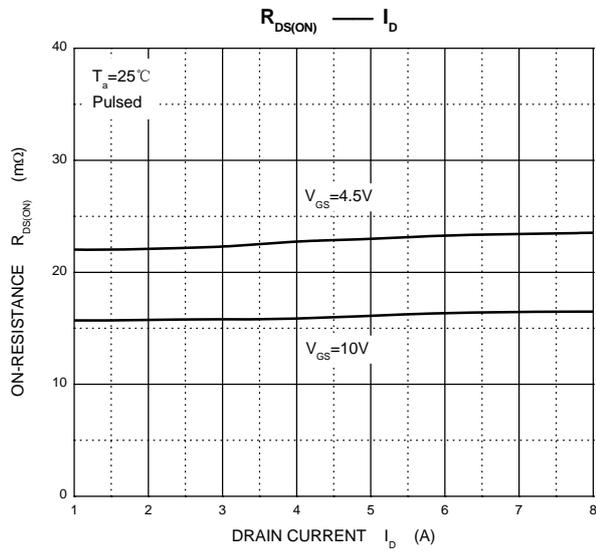
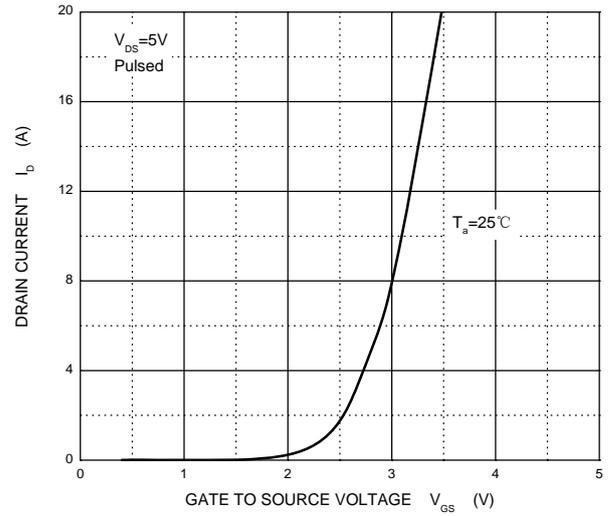
# Typical Characteristics

## N-Channel MOS

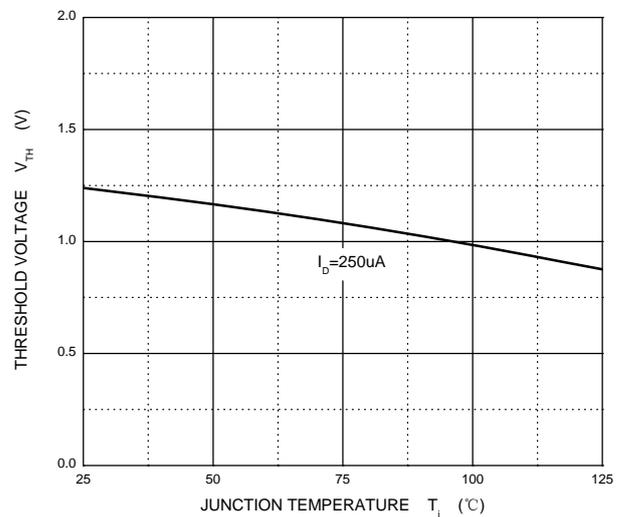
### Output Characteristics



### Transfer Characteristics



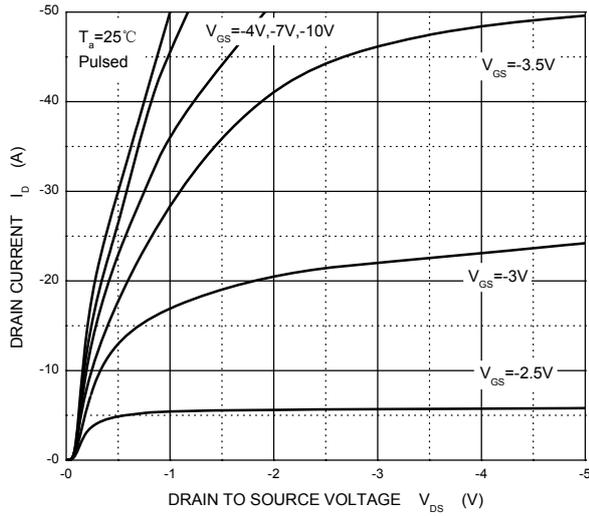
### Threshold Voltage



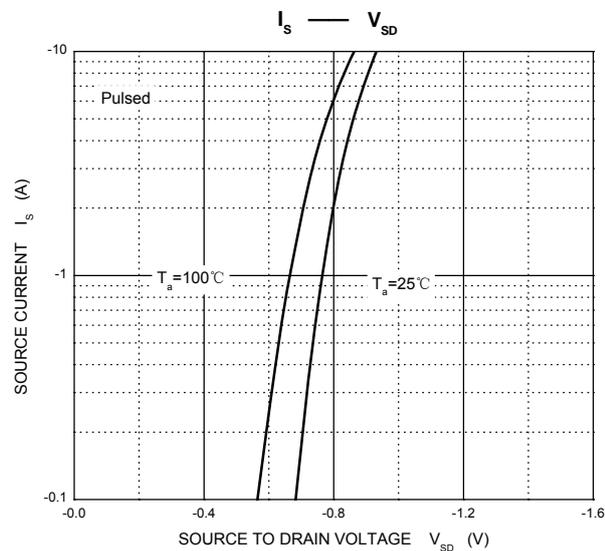
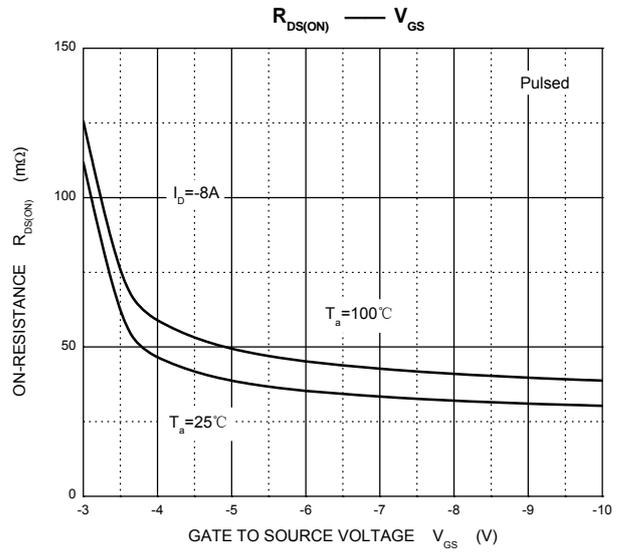
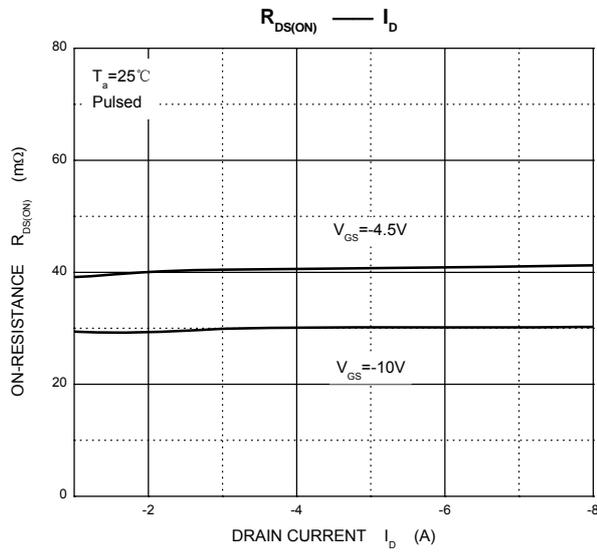
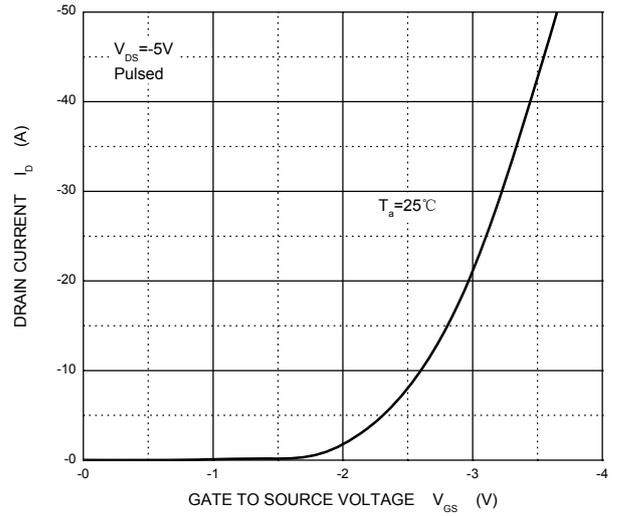
# Typical Characteristics

## P-Channel MOS

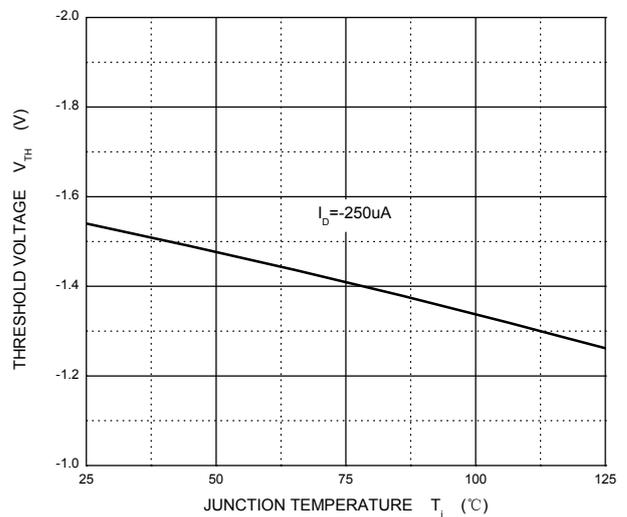
### Output Characteristics



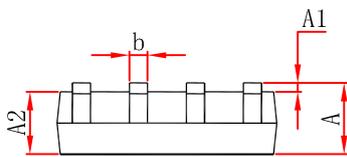
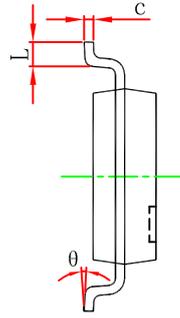
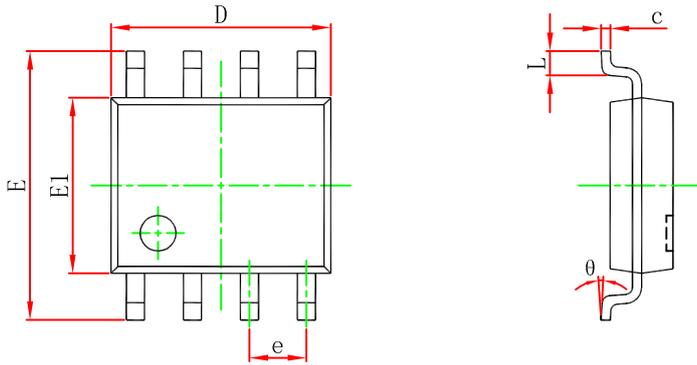
### Transfer Characteristics



### Threshold Voltage

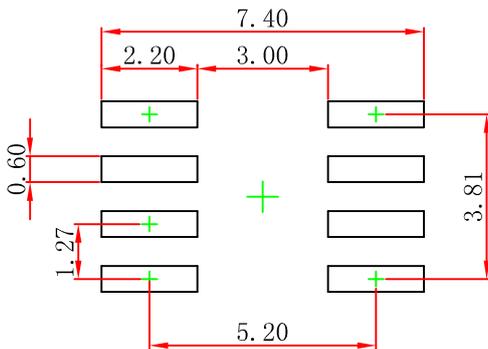


## SOP8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

## SOP8 Suggested Pad Layout



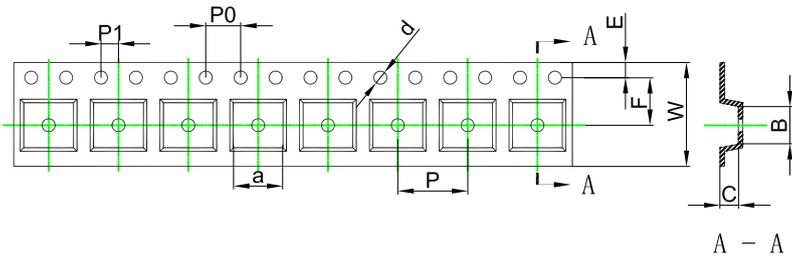
- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05$  mm.
  3. The pad layout is for reference purposes only.

### NOTICE

JCET reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JCET does not assume any liability arising out of the application or use of any product described herein.

# SOP8 Tape and Reel

## SOP8 Embossed Carrier Tape



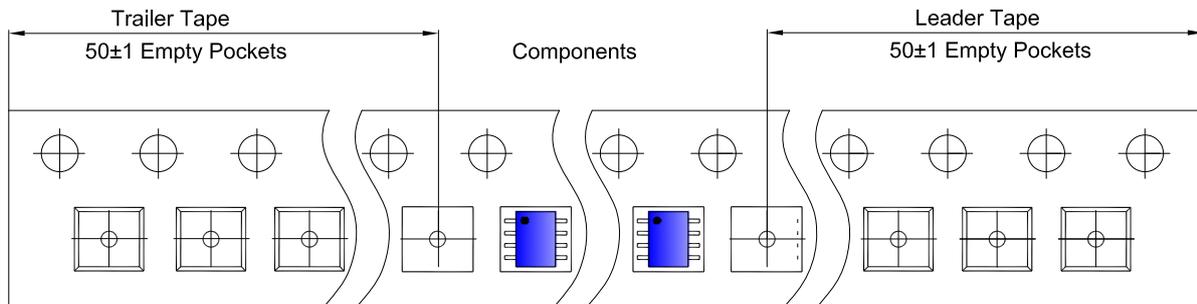
### Packaging Description:

SOP8 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

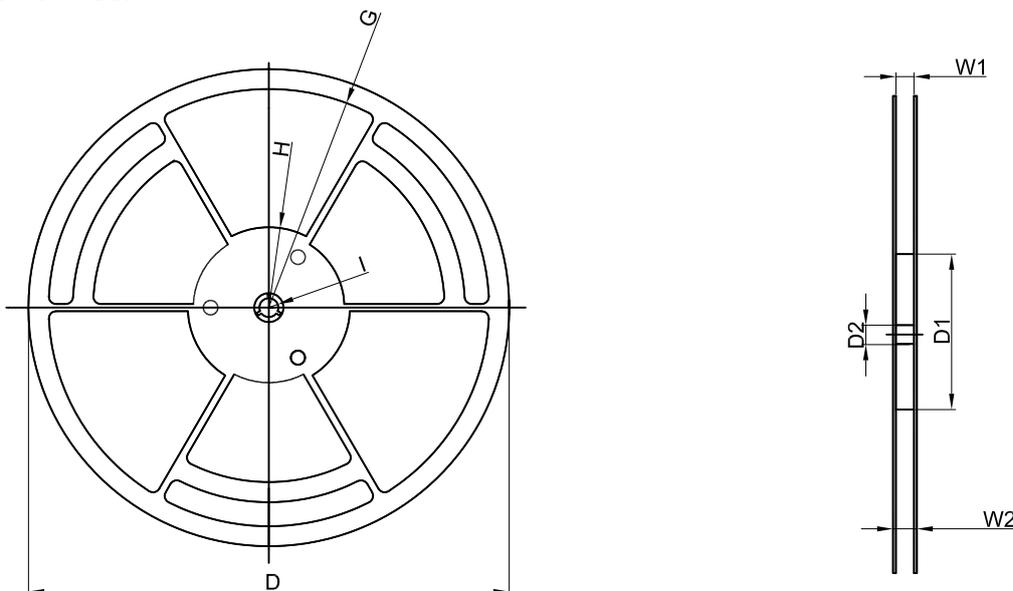
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
SOP8	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

## SOP8 Tape Leader and Trailer



## SOP8 Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13" Dia	Ø330.00	100.00	13.00	R151.00	R56.00	R6.50	12.40	17.60

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
4,000 pcs	13 inch	8,000 pcs	360×360×65	64,000 pcs	565×380×390	